

Form PTO 1449  U.S. Department of Commerce Patent and Trademark Office  Information Disclosure Statement by Applicant	ATTY. DOCKET NUMBER NITT.0063	SERIAL NUMBER To Be Assigned
	APPLICANT KATAGIRI et al.	
	FILING DATE Concurrently Herewith	GROUP

11046 U.S. PTO  
 10/081212  
 02/25/02

U.S. Patent Documents


Examiner Initial	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBC LASS	FILING DATE
AR	5,770,095	6/23/1998	Sasaki et al.	<del>          </del>	<del>          </del>	7/11/1995
AR	5,972,792	10/26/1999	Hudson	<del>          </del>	<del>          </del>	10/18/1996
AR	4,954,142	1/28/1992	Nenadic et al.	<del>          </del>	<del>          </del>	2/23/1999

Foreign Patent Documents

Examiner Initial	DOCUMENT NUMBER	FILING DATE	COUNTRY	CLASS	SUB- CLASS	TRANSLATION	
						YES	NO
AR	2-278822	3/7/1990	Japan	<del>          </del>	<del>          </del>		X
AR	8-83780	3/26/1996	Japan	<del>          </del>	<del>          </del>		X
AR	2000-049122	7/30/1998	Japan	<del>          </del>	<del>          </del>	Abs.	X

Other Documents (Including Author, Title, Date Pertinent Pages, Etc.)

AR	Vilas Koinkar, Reza Golzarian, Quiliang Luo, Matthew Van Hanechem, Jim Shen and Peter Burke, "Chemical mechanical planarization of copper interconnects using fixed abrasive polishing pad," 2000 Chemical Mechanical Planarization for ULSI Multilevel Interconnection Conference", March 2000, pp. 58-65
AR	"New material and process technology for next generation ULSI multi-layered wirings", Technical Information Society, pp. 242-246

EXAMINER		DATE CONSIDERED	04/02/03
----------	---	-----------------	----------

*EXAMINER: Initial if citation is considered, whether or not citation is in conformance with MPEP 609; draw a line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant*